

Day 1 - Monday 15th April 2024

18:30 Pre-conference networking drinks reception

Day 2 - Tuesday 16th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

PIC Packaging: Securing Optimal Integration and Performance

09:00 **Electrooptic Glass Substrates for Photonic Packaging**

Presented by Andreas Matiss - Corning

Industry proven Photonic Wire Bonds and Facet-Attached Micro-Optical Elements: from Telecom/Datacom to Quantum

09:15 **Applications**

Presented by Philipp-Immanuel Dietrich - Vanguard Automation

09:30 **Optimizing Cost and Scaling Efficiency in Swept Wavelength Testing for Alignment and Packaging of PIC**

Presented by Matt Adams - VIAVI Solutions

09:45 **Advancing Optical Testing for Photonic Integrated Circuits: From Prototype to Production Scale-Up**

Presented by Ricardo Arias - Luna Innovations

10:00 **Towards a Comprehensive, Multiphysics Design Solution for Co-packaged Optics**

Presented by Ahsan Alam - Ansys Optics

10:15 **Aligned additive microfabrication for advanced optical packaging**

Presented by Jochen Zimmer - Nanoscribe

10:30 Morning Break

11:00 **Breaking the barriers for high frequency packaging**

Presented by Guillermo Carpintero - LEAPWAVE TECHNOLOGIES

11:15 **Technology Developments & Equipment Concepts for Scaling Up Photonics Production for Datacenters**

Presented by Malte Ennen - ficonTEC

11:30 **As Photonics Applications Multiply, New Ways to Subtract Costs**

Presented by Scott Jordan - Physik Instrumente

11:45 **Advances in PIC Manufacturing for Sensing and Datacom Applications – ALL Thanks to Nanoimprint Lithography**

Presented by Jonas Khan - EV Group

AIM Photonics Foundry providing Co-Process and Co-Development to Address Challenges in Photonic Integrated Circuit (PIC)

12:00 **Packaging**

Presented by David Harame - AIM Photonics

12:15 **Impact of PIC device architecture and integration concept on packaging and assembly**

Presented by Helen Waechter - Helbling Technik Bern AG

12:30 **Advancing the Frontier of Photonic Integration: Challenges and Innovations in PIC Packaging**

PHIX, Lightwave Logic Inc, Tyndall National Institute, and POET Technologies

13:00 Lunch Break

Hybrid PICs: Pioneering New Frontiers in Photonic Integration

Sponsored by OPTICA

14:15 **Designing high power hybrid integrated tuneable lasers for automotive LiDAR**

Presented by Ruud Oldenbeuving - imec

14:30 **Advances in hybrid Silica-Nitride waveguides**

Presented by Henk Bulthuis - Broadex Technologies

14:45 **Unlocking the potential of hybrid/heterogeneous PIC design**

Presented by Martin Fiers - Luceda Photonics

15:00 **TFLN PIC Platform: Unleashing Monolithic power to Enhance Hybrid/Heterogeneous PICs**

Presented by Hamed Sattari - CSEM

High speed, low power, tiny modulators in a polymer PIC platform are poised to enable 800G/1.6Tbps data communications,

15:15 **driven in part by artificial intelligence.**

Presented by Michael Lebby - Lightwave Logic Inc

15:30 **Advanced Photonic Integrated Circuit Testing: APEX Technologies' solution for High Precision Optical Instrumentation**

Presented by Tomy Marest - APEX Technologies

15:45 **BTO-powered PICs for communication and switching**

Presented by Cyriel Minkenberg - Lumiphase

16:00 Afternoon Break

16:30 **Heterogeneous integration to capitalize on upcoming markets, the new IPSR-I global roadmap update**

Presented by Peter van Arkel - PhotonDelta

Advancements in Optically Enhanced MEMS Inertial Sensors: Prototyping and Roadmap Challenges for Consumer Markets

16:45 **(Video presentation)**

Presented by Lia Li - Zero Point Motion

17:00 **Augmented Silicon Photonics for demanding Data Center and AI/ML network fabrics**

Presented by Yannick Paillard - SCINTIL Photonics

- 17:15** **Silicon-organic hybrid electro-optic modulators for next generation optical interconnects**
Presented by Adrian Mertens - SilOrix
- 17:30** **Heterogeneous Integration of Photonic Devices on Silicon**
Presented by Jonathan Klamkin - UCSB (University of California Santa Barbara)
- 17:45** **Photonic Integrated Circuits: Surface Coupling Lasers using InP as an integration platform**
Presented by Bill Ring - Vector Photonics
- 18:00** **Sputter deposited Al₂O₃: an ultra-low loss integrated photonic platform for broadband operation from the UV till the mid-IR**
Presented by Sonia M. Garcia-Blanco - ALUVIA Photonics
- 18:15** **Closing Remarks**
- 18:20** **Networking Drinks / Dinner Reception**

Day 3 - Wednesday 17th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Rapid Scaling: Foundries Fuelling PICs' Mass Production

- 09:00 **A view from the Foundry: Silicon Photonics**
Presented by Anthony Yu - GlobalFoundries
- 09:15 **Low Loss Photonic Integrated Circuits: From Prototype to Volume**
Presented by Michael Geiselmann - LIGENTEC
- 09:30 **Silicon photonics for AI/HPC Optical Interconnects**
Presented by Philippe Absil - imec

Power Efficiency: Minimizing Consumption in PICs

- 09:45 **The evolving role of optics in AI Clusters**
Presented by Vlad Kozlov - LightCounting

PIC Size and Simulation: Enhancing Design Efficiency

- 10:00 **A perspective on recent trends in inverse design of integrated photonic devices and circuits**
Presented by Wolfer Peelaers - Hewlett Packard Enterprise
- 10:15 **Efficient design techniques for custom PDKs protecting your IP**
Presented by Andrzej Pożatynski - VPIphotonics

10:30 Morning Break

Accelerating PIC Adoption in Established Markets

Sponsored by LioniX International

- 11:10 **Design to Device: Accelerating PIC adoption by lowering entry barriers to turnkey photonic solutions**
Presented by Amitesh Singh - LioniX
- 11:25 **Transforming point-of-care diagnostics: The power of silicon plasmonic biosensors in the battle against acute infections**
Presented by Dimitris Tsiokos - bialoom
- 11:40 **Is integrated optics a perfect fit for next generation of Access Networks?**
Presented by Prof. Dr. Antonio Teixeira - PICadvanced
- 11:55 **Innovate with Confidence: Strategies for reliable PIC design**
Presented by Ronald Broeke - Bright Photonics
- 12:10 **Scaling photonic integration and packaging of hybrid multi-chip assemblies using 3D lithography**
Presented by Dr. Laura Horan - Vanguard Automation
- 12:25 **Opportunities for Photonics in Datacenter and High-Performance Computing (HPC) Infrastructure**
Presented by Remco Stoffer - Synopsys
- 12:40 Lunch Break
- 13:55 **Silicon Photonics Market and Applications: from Optical Transceivers to Emerging Uses**
Presented by Eric Mounier - Yole Group
- 14:10 **Semiconductorization of Photonics using Silicon Optical Interposer**
Presented by Raju Kankipati - POET Technologies
- 14:25 **Efficient Test of PICs for High-Performance Computing Applications**
Presented by Daria Lavrova - Keysight Technologies
- 14:40 **Revolutionizing Architecture and Components for New Generation Energy-Efficient High-Density Photonic Integrated Coherent Transceivers**
Presented by Tomoyuki Akiyama - PETRA/Fujitsu
- 14:55 **Opportunities and Challenges for Optics in AI Factories**
Presented by Yannick De Koninck - NVIDIA
- 15:10 **PIC Solutions for Established and Novel Optical Communication Applications**
Presented by Mehrdad Ziari - Infinera
- 15:25 **Opportunities for Silicon Photonics: Developments and Applications**
Presented by James Falkiner - IDTechEx
- 15:45 Closing Remarks

NOTES

This image shows a single sheet of white paper with horizontal ruling lines. The lines are evenly spaced and run across the width of the page. There are no margins, text, or other markings on the paper.